



Material Content Data Sheet



Sales Product Name	TLF4949SJ			Issued	1. August 2018			
MA#	MA001001404							
Package	PG-DSO-8-44			Weight*	82.59 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.577	0.70	0.70	6987	6987
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		109	
	non noble metal	zinc	7440-66-6	0.036	0.04		434	
	non noble metal	iron	7439-89-6	0.717	0.87		8684	
wire	non noble metal	copper	7440-50-8	29.121	35.26	36.18	352599	361826
	non noble metal	copper	7440-50-8	0.083	0.10	0.10	1002	1002
	encapsulation	organic material	carbon black	1333-86-4	0.101	0.12		1219
	plastics	epoxy resin	-	4.630	5.61		56057	
		inorganic material	silicondioxide	60676-86-0	45.593	55.20	60.93	552041
leadfinish	non noble metal	tin	7440-31-5	0.814	0.99	0.99	9854	9854
plating	noble metal	silver	7440-22-4	0.650	0.79	0.79	7873	7873
glue	plastics	acrylic resin	-	0.057	0.07		691	
		noble metal	silver	7440-22-4	0.202	0.24	0.31	2450
*deviation	< 10%			Sum in total:		100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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